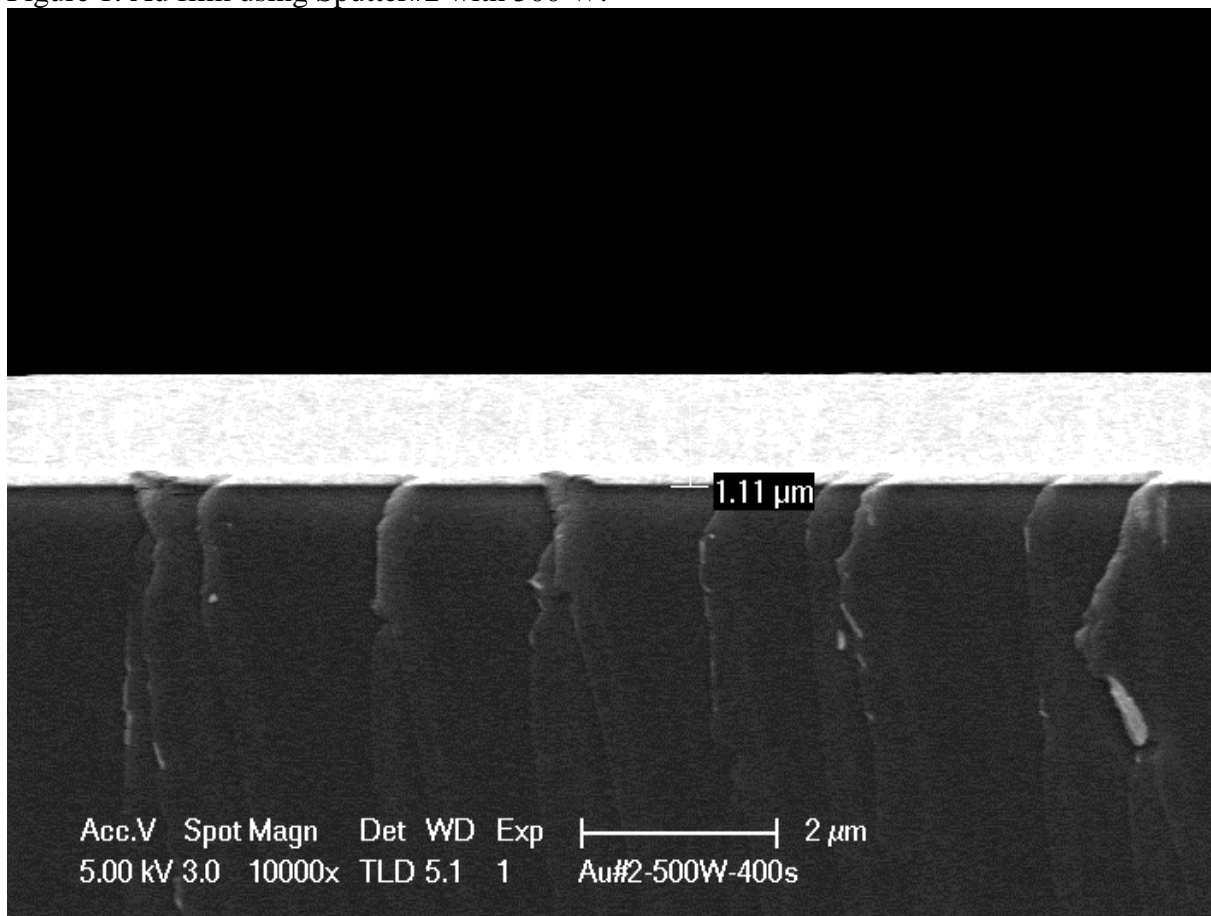


Au Film Sputtered using Sputter#2 (PM5)							
Wafer#	Power (W)	Ar Flow-rate (sccm)	Deposition Time (s)	Au Film Thickness (Å)	Deposition Rate (Å/s)	Resistivity (Ωcm)	Stress (MPa)
1	500	15	400	11100	27.8	3.66E-06	234
2	1000	10	200	11100	55.5	3.88E-06	313
3	2000	10	100	10300	103	3.94E-06	349

Figure 1. Au film using Sputter#2 with 500 W.



Ning Cao and Brian Thibeault, Staff, Nanofab Lab, UCSB

Figure 2. Au film using Sputter#2 with 1000 W.

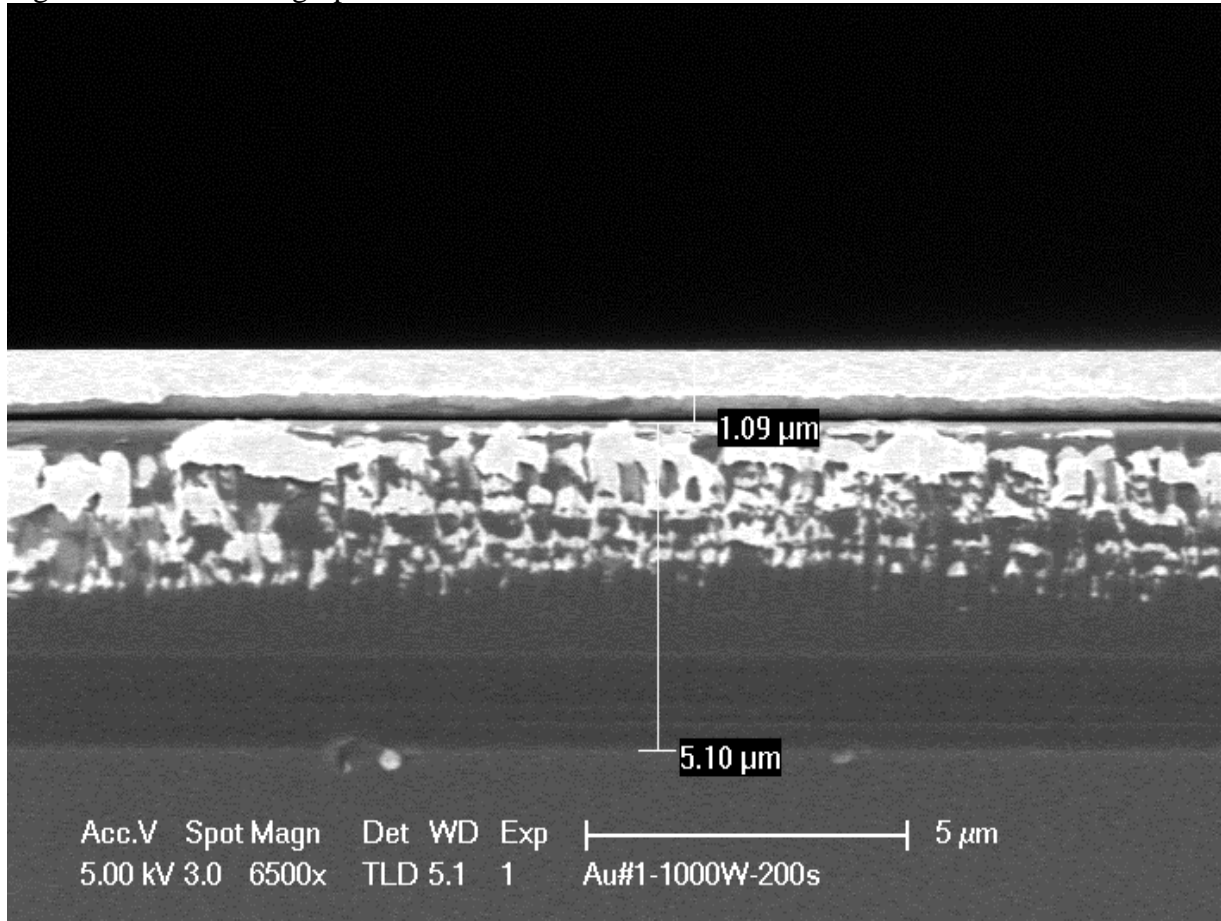


Figure 3. Au film using Sputter#2 with 2000 W.

